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Bandwidth Investigation on Half-height Pin in Ridge Gap Waveguide

Fangfang Fan, Member, IEEE, Jian Yang, Senior Member, IEEE, Vessen Vassilev, and Ashraf Uz Zaman, Member, IEEE

Abstract—Gap waveguide is a promising transmission structure, especially for millimeter wave and terahertz applications. That it does not require conductive connection between the upper and the lower plates makes this technology gain advantages over conventional rectangular waveguides and substrate integrated waveguides (SIW) in millimeter-wave and terahertz regime. Different fabrication methods for gap waveguides should be employed for different frequency bands applied, such as molding, milling, die forming, electrical discharge machining (EDM), microelectromechanical systems (MEMS), 3D printing. Therefore, different pin forms used in gap waveguides are required to match the applied fabrication methods. In this paper, a new pin form, the half-height pin form, in gap waveguides is proposed for reducing the fabrication cost, and its stopband characteristics are investigated and compared to the previous full-height pins in gap waveguides at V band. A device of a double-ridged gap waveguide with two 90° bends for verifying the stopband characteristic analysis of the new pin form has been designed and manufactured. The measured data confirms our analysis and simulations.

Index Terms—gap waveguide, half-height pin gap waveguide, stopband bandwidth.

I. INTRODUCTION

DURING the last couple of years, a new transmission structure, the so-called gap waveguide, has been proposed for millimeter wave (mmW) and terahertz applications [1], and a series of components based on this technology, such as power dividers, filters, couplers, and antennas, have been designed and verified experimentally [2]–[9]. The gap waveguides have been realized until now by two parallel metal plates, with periodic metal pins on the lower plate to play the role of Artificial Magnetic Conductor (AMC) and smooth surface on the upper plate. No electromagnetic waves can propagate through this pin structure, except along some guiding configurations, such as ridges in ridged gap waveguides [10], microstrip lines in inverted microstrip line gap waveguides [11] or grooves in groove gap waveguides [12], under the condition that the gap between the top of the pins and the upper plate is less than quarter wavelength. Since the waves propagate only along the guiding configurations where the electromagnetic waves are constrained in the air in all types of gap waveguides, there is no dielectric losses, even that dielectric substrates are involved in the structure of inverted microstrip line gap waveguides. Thus, the gap waveguides have the advantage of lower loss compared to microstrip lines and substrate integrated waveguides (SIW), where the waves propagate in dielectric materials.

The fact that it does not require conductive connection between the upper and the lower plates in gap waveguides opens up a lot of possibility and availability for many cost-effective manufacture technologies to be used in mmW and terahertz devices and systems by gap waveguide technology, such as molding, milling, die forming, electrical discharge machining (EDM), microelectromechanical systems (MEMS) and 3D printing. Different fabrication technologies have their own characteristics. Therefore, an optimal fabrication technology should be selected for low-cost manufacture for different pin geometries in gap waveguides. Until now, the existing pin forms are the circular pins [13], the square pins [1], the inverted pyramid-shaped pins [14] and the double cone pins [15]. The first two are the basic forms and the last two are for wideband performance. However, all these pins are quite
long and thin at mmWs, which poses a difficulty for low-cost manufacture.

The purpose of this paper is to propose and analyze a new pin form: the half-height pins [16], [17] for relaxing the fabrication requirements with the same electrical performance. The paper is organized as follows. In Sect. II we describe characteristics of different fabrication technologies applied to the gap waveguide technology and therefore the motivation of the present work. An analytical model for the new pin structure is set up in Sect. III to describe the basic working principle. Analysis and discussions on the stopband characteristics of the half-height pins with different dimensions are presented in Sect. IV. The misalignment tolerance between the upper pins and the lower pins is analyzed in Sect. V. A device of a double-ridged gap waveguide (DRGW) with two 90° bends for verifying the stopband characteristics of the new pin form is designed and presented in Sect. VI with measurement data. Then, the paper is ended with conclusions.

II. FABRICATION TECHNOLOGIES IN GAP WAVEGUIDE TECHNOLOGY

Different fabrication technologies have their own advantages and disadvantages, and therefore a certain applicability in the gap waveguide technology.

1) **Molding** is a very cheap fabrication method for mass production. The main drawbacks of this technique for gap waveguide pins are that the pins cannot be thin and long, and the surface is not smooth enough for mmW applications. We have not yet tried this manufacture technique since we are still in the development stage.

2) **Milling** is an accurate technique for gap pins below 100 GHz. Fig. 1(a) shows a pin structure for a gap waveguide by milling. The main drawbacks of this technique are that the pins cannot be thin and long, and the cost is not low enough for mass production.

3) **Die Forming** uses a high pressure on a soft metal material through a die to make pins, as shown in Fig. 1(b), and is a good technique for mass production. The main problem is that it is very difficult to separate the die and the pin plate if the pins are long and thin.

4) **EDM** is a manufacturing process whereby a desired shape is obtained using electrical discharges, as shown in Fig. 1(c). The main problem is that the pins should not be long and thin, and the die for discharge can be used only for a limited number of times, which makes the mass production cost not very low.

5) **MEMS** makes dielectric pins by “growing” and then gold surface plating them, which is efficient for gap waveguide pins above 100 GHz for mass production. A pin structure at 300 GHz is shown in Fig. 1(d). However, it is very difficult and expensive for MEMS to make pins at 60 GHz (about 1.25 mm long). If the pin’s length at 60 GHz can be short as half (about 0.6 mm long), MEMS becomes attractive for 60-GHz pin structures.

6) **3D printing** can only print at the moment plastic pin structure with good tolerance and smooth surface as shown in Fig. 1(e) (direct printing in metal leads to a rough surface which causes a large loss at mmW) and then the 3D plastic pin structure should have metal surface plated, which may cause a rough surface. 3D printing prefers short and thick pins. In addition, 3D printing is not a choice for mass production. It can be concluded from the above that short and thick pins are much preferred for all manufacture techniques. This is our motivation to propose and analyze the half-height gap waveguide pin form.

III. NEW PIN FORMS AND ANALYSIS MODEL

Fig. 2(a) shows the geometry of the new half-height pin. As a reference, the previous developed square pin form, referred to as the full-height pin in this paper, is presented in Fig. 2(b).
The half-height pin in Fig. 2(a) has the air gap between the upper and the lower pin plates. From the simulations shown in the next section, the optimal value of the pin’s length is a half of the previous developed pins, which is the reason for its name.

The half-height pin form has a symmetry between the upper and the lower plates. The upper PEC (perfect electric conductor) and the lower PMC (perfect magnetic conductor) model for full-height pin gap waveguides is not valid for the half-height pin structure. An analysis model of a general pin form for gap waveguides is shown in Fig. 3(a): each pin (or each pair of the upper and the lower pins in our case) can be modeled by an admittance $jB$ in a parallel-plate waveguide. All propagating waves are composed by two basic modes: $x$-direction propagating waves and $y$-direction propagating waves. A stop band is held when and only when no propagating waves. A stop band is held when and only when

$$0.5|A + D| = |\cos \theta - \frac{b_0}{2} \sin \theta| > 1$$

where $\theta = k(p - w)$, with the propagation constant $k$ of the parallel-plate waveguide, $p$ the length of the period for unit cell, and $w$ the width of the pin. From [18], the requirement for no wave propagation in the pin structure is

$$0.5|A + D| = |\cos \theta - \frac{b_0}{2} \sin \theta| > 1$$

IV. STOPBAND ANALYSIS FOR HALF-HEIGHT PINS

The CST model is shown in Fig. 4 for analyzing a half-height pin unit with $p = 1.71$ mm, $d = 1.31$ mm, $w = 0.79$ mm, $h = 0.125 \lambda_{60GHz}$, $h = 0.0625 \lambda_{60GHz}$, and $h = 0.0125 \lambda_{60GHz}$.
mm and \( h = 0.26 \) mm. The two PMC side walls are defined in order to make the periodical structure in \( y \)-direction. The \( ABCD \) matrix of the unit cell can be extracted from CST simulated data. The simulated value of \( 0.5|A + D| \) is shown in Fig. 4, indicating that the stopband is from 43.68 GHz to 109.40 GHz (where \( 0.5|A + D| > 1 \)). The same structure has been also full-wave analyzed by using the Eigenmode solver in CST, which gives a stopband from 43.28 GHz to 106.52 GHz. Therefore, the model for operation mechanism of the general pin form by using equivalent circuit method has a satisfactory accuracy and can be used to understand the working principle of the half-height pin gap waveguide.

The stopband characteristics of the half-height pin form have been investigated by using both the above mentioned analysis model and numerical software CST Eigenmode solver. We choose the narrower bandwidth from the two methods in order to guarantee the wave stop. The stopband characteristics of half-height pins, both the bandwidth and the center frequency of stopband, are varied with all pin’s parameters: period \( p \), width \( w \), gap height \( h \) and length \( d \). Therefore, we choose to present the stopband characteristics with two varied parameters and two fixed parameters with frequencies normalized by 60 GHz in each of figures from 5 to 8.

Fig. 5 shows both the upper \( f_{\text{max}} \) and the lower \( f_{\text{min}} \) limits of the stopband for both the half-height and the full-height pin forms with fixed values of \( p = 0.25\lambda_{60\text{GHz}} \) and \( d = 0.25\lambda_{60\text{GHz}} \), and varied values of \( w \) and \( h \). Note that \( \lambda_{60\text{GHz}} \) is the wavelength at 60 GHz, not the center frequency of the stopband. It can be seen from Fig. 5 that the stop bandwidth for both pin forms is enlarged when \( h \) decreases, and the optimal value of \( w/p \) for the largest ratio bandwidth \( f_{\text{max}} : f_{\text{min}} \) is 0.5–0.7 for the half-height pins and 0.3–0.5 for the full-height pins, respectively. In addition when \( w/p = 0.8 – 0.9 \) (very thick pins) with \( h = 0.0125\lambda_{60\text{GHz}} \), the stop bandwidth is about 2.7:1 for the half-height pins but 2:1 for the full-height pins. This indicates that the half-height pin gap waveguide can have thicker and shorter pins than the full-height pin gap.
The case of varied \( p \) and \( w \) with \( d = 0.25\lambda_{60\text{GHz}} \) and \( h = 0.0625\lambda_{60\text{GHz}} \) is shown in Fig. 7. The optimal value of \( p \) for the largest stop bandwidth is about \( 0.375\lambda_{60\text{GHz}} \) for both the half-height and the full-height pins, and the stop bandwidth is about \( 1.6 : 1 \) for the half-height pins and about \( 1.3 : 1 \) for the full-height pins when \( w/p = 0.9 \).

Fig. 8 shows the results for varied \( w \) and \( d \) with \( p = 0.25\lambda_{60\text{GHz}} \) and \( h = 0.0625\lambda_{60\text{GHz}} \). From the figure, it can be seen that with the increase of \( d \), both the upper \( f_{\text{max}} \) and the lower \( f_{\text{min}} \) limits shift to lower frequencies with almost unchanged stop bandwidth, which is expected. So \( d \) has no influence on the bandwidth but determines the center frequency of the stopband.

From all the results shown above, we can conclude: 1) The air gap \( h \) is a main factor to define the stop bandwidth. The smaller \( h \), the larger stop bandwidth, for both the half-height pin and the full-height pin forms. 2) Larger pin width does not reduce the stop bandwidth significantly for the half-height pin and (b) Full-height pin.

From the figure, we can conclude for this case that smaller \( h \) makes larger stop bandwidth, and the optimal values of \( p \) for the largest stop bandwidth are between \( 0.25\lambda_{60\text{GHz}} \) and \( 0.375\lambda_{60\text{GHz}} \), for both the half-height pin and the full-height pin forms.
Fig. 12. Application example of half height pin gap waveguides: a V-band 8 × 8 slot array antenna using half height pins for feeding network: (a) Geometry of the antenna; (b) Prototype (left) and a side view (right) through pins to show a good alignment for the whole antenna by checking the alignment of upper and lower pins.

Fig. 13. CST models of the verification devices of two 90° bends: (a) With many rows of pins; (b) With only two rows of pins, where all dimensions are listed in Table I.

pins but does for the full-height pins. 3) Period $p$ has also a significant influence on the stop bandwidth, so $p$ should be between 0.25λ and 0.375λ. 4) The pin length $d$ determines the center frequency of the stopband.

V. TOLERANCE ANALYSIS OF MISALIGNMENT

One natural question arises with the introduction of the half-height pin structure: how does a misalignment between the upper and the lower pins affect the performance? A tolerance analysis of this misalignment has been carried out with simulations in CST Microwave Studio.

Fig. 9 shows the models of an offset pin unit cell and an offset DRGW for the stopband analysis in CST. The dimensions of the offset pin cell and the DRGW are illustrated in Fig. 13 and Table I except for offset $a$ which will vary for the analysis. Fig. 10 shows the simulated stopband with different values of offset $a$ for both the offset pin structure and the offset DRGW. It can be seen that the stopband decreases with the increase of offset $a$ and that the stop bandwidth with the DRGW offset or non-offset is smaller than that of only the pin structure offset or non-offset. This is because the definition of the stopband for ridged gap waveguides is the band where all modes are stopped to propagate except for the quasi-TEM mode (the dominate mode in the ridge gap waveguide) along the ridges. Since higher order modes in the DRGW appear before the pin structure propagation modes, the stop bandwidth for DRGW is reduced. For example, with the full offset ($a = 1.05$ mm) where the upper pin are in the middle of the lower pin, there is still a narrow stopband from 30 GHz to 50 GHz for the pin structure. However, when the DRGW is offset with $a$ larger than 1 mm, there is no stopband, which means that higher order DRGW modes can propagate along the ridges at the same time with the quasi-TEM mode. Nevertheless, if offset $a$ is smaller than 0.4 mm for the gap


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**TABLE I**

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value (mm)</th>
<th>Parameter</th>
<th>Value (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>$d/2$</td>
<td>0.7</td>
<td>$L_1$</td>
<td>20.575</td>
</tr>
<tr>
<td>$w$</td>
<td>1.25</td>
<td>$L_2$</td>
<td>10.5</td>
</tr>
<tr>
<td>$h$</td>
<td>0.118</td>
<td>$L_3$</td>
<td>20.375</td>
</tr>
<tr>
<td>$p$</td>
<td>2.1</td>
<td>$w_{ridge}$</td>
<td>1.8</td>
</tr>
</tbody>
</table>
waveguide (a very large value for manufacture tolerance), the stopband is kept almost unchanged from 40 GHz to 72 GHz.

Fig. 11 shows another investigation on the offset tolerance: two parallel double-ridged lines are separated by two rows of the half-height pins with or without a misalignment of offset $a = 0.3$ mm between the upper plate and the lower plate (so both the ridges and pins are offset). The figure shows that the S-parameters, both the reflection coefficient $S_{11}$ and the mutual couplings $S_{31}$ and $S_{41}$ among port 1, port 3 and port 4, are almost unchanged with this misalignment. Therefore, we can conclude that if offset $a$ is smaller than 20% of the width of the pins, the performance of the half-height pin gap waveguide is almost not affected by the misalignment offset.

It is worth pointing out that even for full-height pin gap waveguide antennas, the alignment is also very critical since anyway a feeding network should have a good alignment to coupling slots or cavities, etc., in a whole antenna structure. Actually, by using the half-height pin gap waveguide, a good alignment can be easily achieved. Fig. 12 shows a planar array antenna prototype with half-height pins, where a good alignment was achieved by aligning the upper pins with the lower pins through the side openings, instead of using expensive and difficult positioning posts for alignment. Please refer to [19] for detailed design of the slot array antenna using the half-height pins at V-band.

For the tolerance analysis, the misalignment tolerance is the one only half-height-pin gap waveguides have. The other dimension tolerance requirements, i.e. pin width $w$, pin length $d$, gap height $h$ and pin period $p$, can be indicated from Fig. 5 to Fig. 8 for both the half height pins and the full height pins. For example, from Fig. 5 if we assume a fixed $p$, the variation of $w$ affects the stop bandwidth in the half-height-pins’ case less than in the full-height-pins’ case with the optimal values of $w/p$ over 0.5–0.7 for the half height pins and over 0.3–0.5 for the full height pins. Figs. 6–8 show the same conclusion that the half height pins have better tolerance performance due to that the curves for half height pins are flatter than those for the full height pins.

VI. VERIFICATION AND MEASUREMENTS

To verify the transmission characteristic of the gap waveguide using the half-height pin form, a prototype of a DRGW with two 90° bends and transitions to microstrip lines at the two ends has been fabricated and measured.
A. Two 90° Bends

The CST model of the verification device with a DRGW employing half-height pins, by PEC, lossy Copper (annealed) \( (\sigma = 5.8 \times 10^7 \, \text{S/m}) \) and PEC with only two rows of the pins, is shown in Fig. 13. It has two 90° bends. The reason to use the two-90°-bend for the verification is that the bends introduce higher order modes at the positions of the bends, and therefore it is a tougher test than a straight line to see if the half-height pins can stop all propagating modes in the pin structure. The dimensions of the pins, ridge and bends are shown in Table I. The simulated S-parameters are shown in Fig. 14, over the frequency band from 35 GHz to 70 GHz, with \( S_{11} \) below -15 dB. It can be seen that the leakage loss is very small (close to 0 dB) based on \( S_{11}^2 + S_{21}^2 \) for the models by PEC, even with only two rows of the pins (hardly see the difference between the PEC model with many rows and only two rows of the pins), and the ohmic loss due to the lossy Copper is from 0.5 dB to 0.8 dB over the frequency band, a major factor for losses. The field distribution of the two-90°-bend from 30 GHz to 70 GHz is shown in Fig. 15, stating a very good propagation only along the double ridge gap waveguide with only two rows of the pins.

A full analysis of Q factor and losses of half-height-pin double-ridged gap waveguides and groove gap waveguides has been presented in [20], where it is concluded that half-height-pin gap waveguides have the nearly identical Q factors as full-height-pin gap waveguides.

B. Transition from Gap Waveguide to GCPW

We use in this work a wideband (35 GHz to 70 GHz) transition from the DRGW to microstrip line (\( \mu \text{stripLine} \)) and then to grounded coplanar waveguide (GCPW) for measuring the verification device with a wafer-probe, instead of using two transitions from DRGW to two standard rectangular waveguides presented in [17]. A similar transition from a microstrip line to a full-height pin ridge gap waveguide was reported in [21]. Fig. 16 shows the diagram of the transition: the PCB of Rogers RO4350B with \( \varepsilon_r = 3.66 \) and 0.118 mm thick (the same as the air gap of the DRGW) is inserted into the middle of the double ridge with the top ridge touching the microstrip line. Four screws are used to connect the back bottom via-hole metal layer to get the grounding. The simulated S-parameters of the whole verification device (two-90°-bend DRGW + two DRGW-\( \mu \text{stripLine}-\text{GCPW} \) transitions) are shown in Fig. 17, with and without a misalignment of \( \alpha = 0.1 \, \text{mm} \). It can be seen that \( S_{11} \) is a bit high (about -5 dB) at both ends of the frequency band due to such a wide bandwidth for DRGW-\( \mu \text{stripLine}-\text{GCPW} \) transitions but not very sensitive to the misalignment so we decide to design and manufacture our own TRL calibration kit as shown in Fig. 18 to calibrate out the effects of the transitions and the connection between GSG probe and the GCPW. Note that the figure shows only the THRU and the LINE while the REFLECT is made by inserting a piece of Copper strip between the upper ridge and the lower ridge, which could not be shown in the figure.

C. Measured Results

Fig. 18 shows the TRL cal kit and the verification device, manufactured by a computer numerical control (CNC) milling machine. The PCBs of the transitions were fabricated by standard photolithography process. All strips on the PCB are gold plated to guarantee a good conductive contact with the wafer-probe for the measurement. A comparison of the size between the present half-height pins and the previous full-height pins is also shown in Fig. 18 with the same scaled photos, which tells that the half-height pins can be much shorter and thicker than the full-height pins, providing a possibility for low-cost pin manufacture. The measurement setup is shown in Fig. 19. The measurement result after calibration process by using the TRL calibration kit is shown in Fig. 20. Note that we can only measure up to 67 GHz due to the limitation of our GSG probe. Compared to the red curve for lossy Copper modeling in Fig. 14, the measured reflection coefficient \( S_{11} \) agree well with the simulated data, and the insertion loss \( S_{21} \) is between 0.3 dB and 0.5 dB lower than the simulated data, which we believe is due to the surface roughness. However, we have no means to measure the surface roughness at the moment so we haven’t verified this statement by simulations.

VII. CONCLUSION

A new pin form for the gap waveguide technology, the half-height pins, was proposed and analyzed. From the analysis, simulations and measurements, the half-height pins have just a half length of the full-height pins, and can have a wider pin width than the full-height pins, with a similar electrical performance on stopband. The tolerance for the misalignment between the upper and the lower pins should be smaller than 20% of the width of the pins. A verification device, the two-90°-bend with the transitions of DRGW-\( \mu \text{stripLine}-\text{GCPW} \) was designed, fabricated and measured. The measured data agreed well with the simulated one. The half-height pin gap waveguide provides a possibility to have a low cost for mass production by different manufacture technology.
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